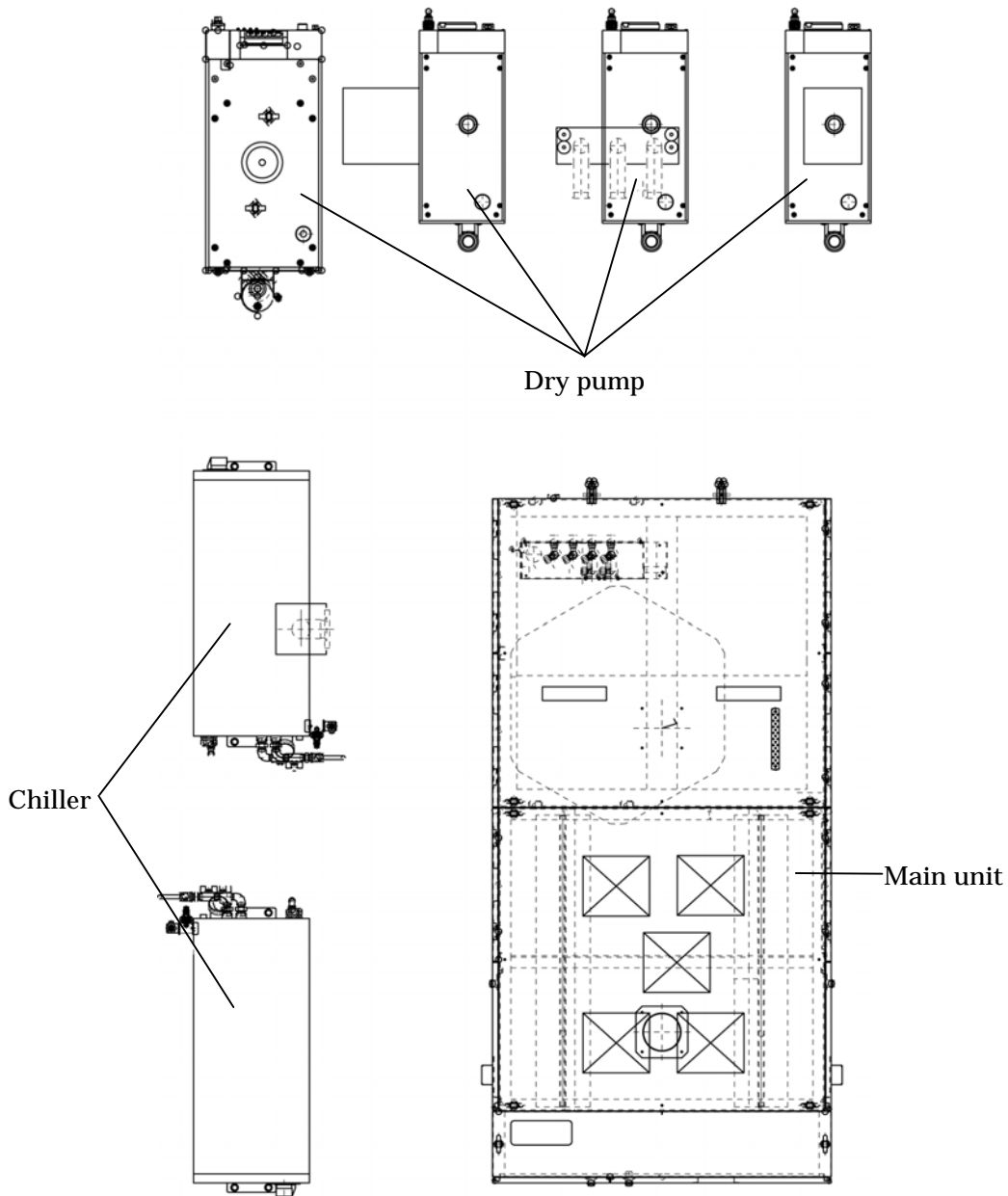


## Chapter 2 General description of the system

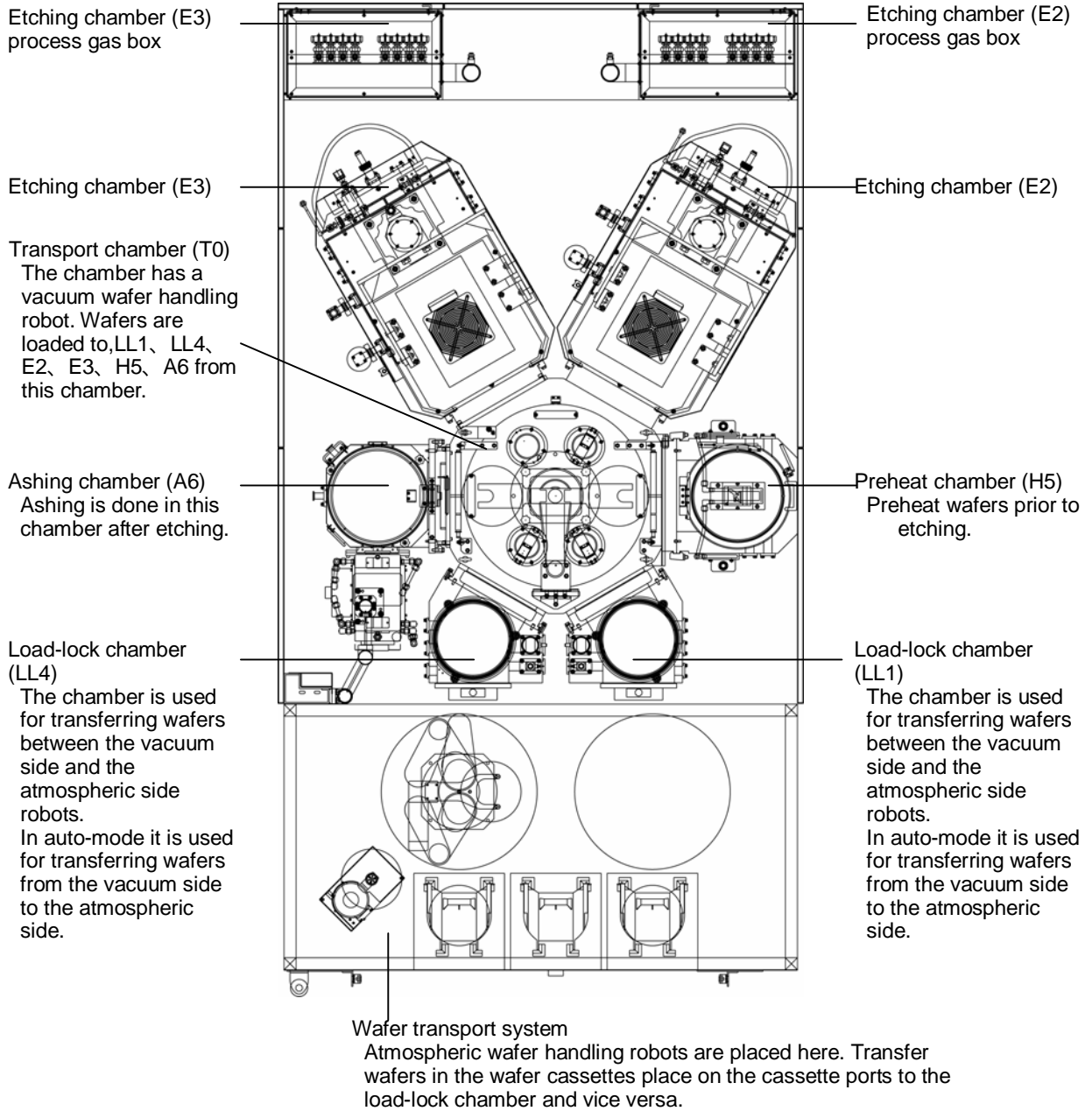
This system is a high density plasma etching system having a C to C load-lock system and an ISM (Inductive Super Magnetron) plasma source.

The system consists of a 200mm Si wafer autoloader (with an aligner), a transport chamber, a pre-heat chamber, reactors, a power supply cabinet, a control unit cabinet, dry pumps, and chillers for cooling reactor electrodes. The system incorporates each system unit such as a controller.

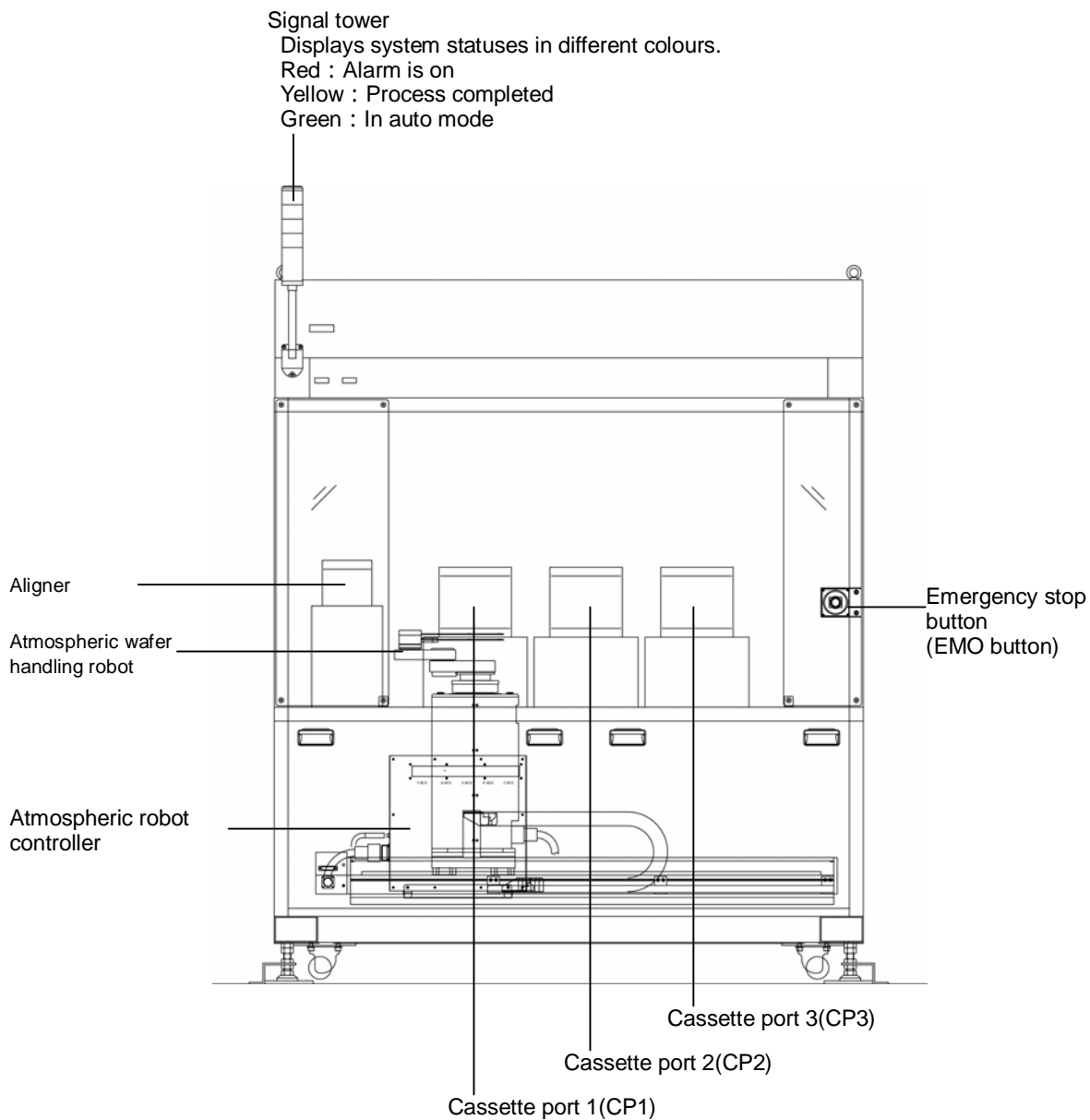
### 2-1. System components



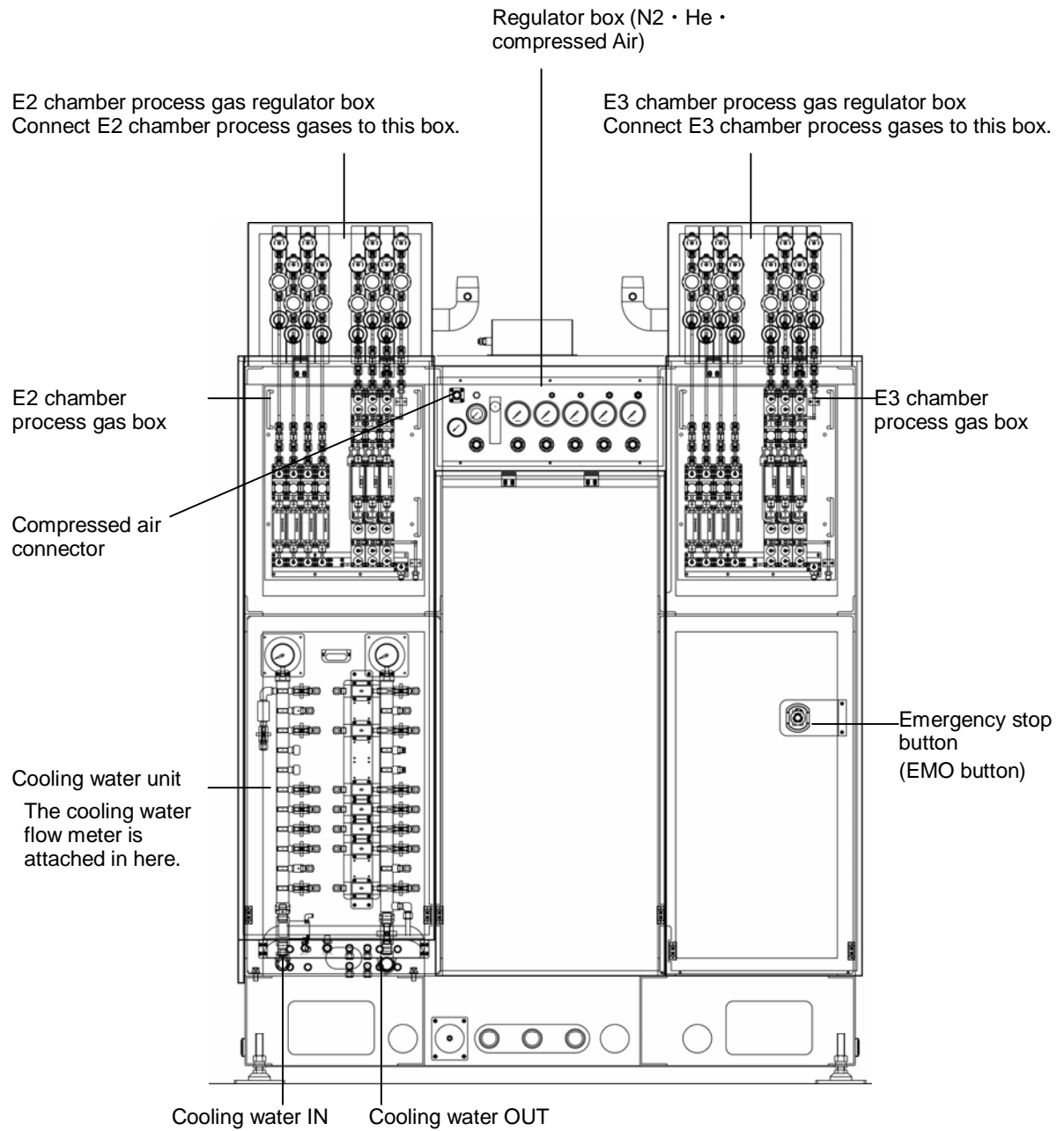
## 2-2. System top view



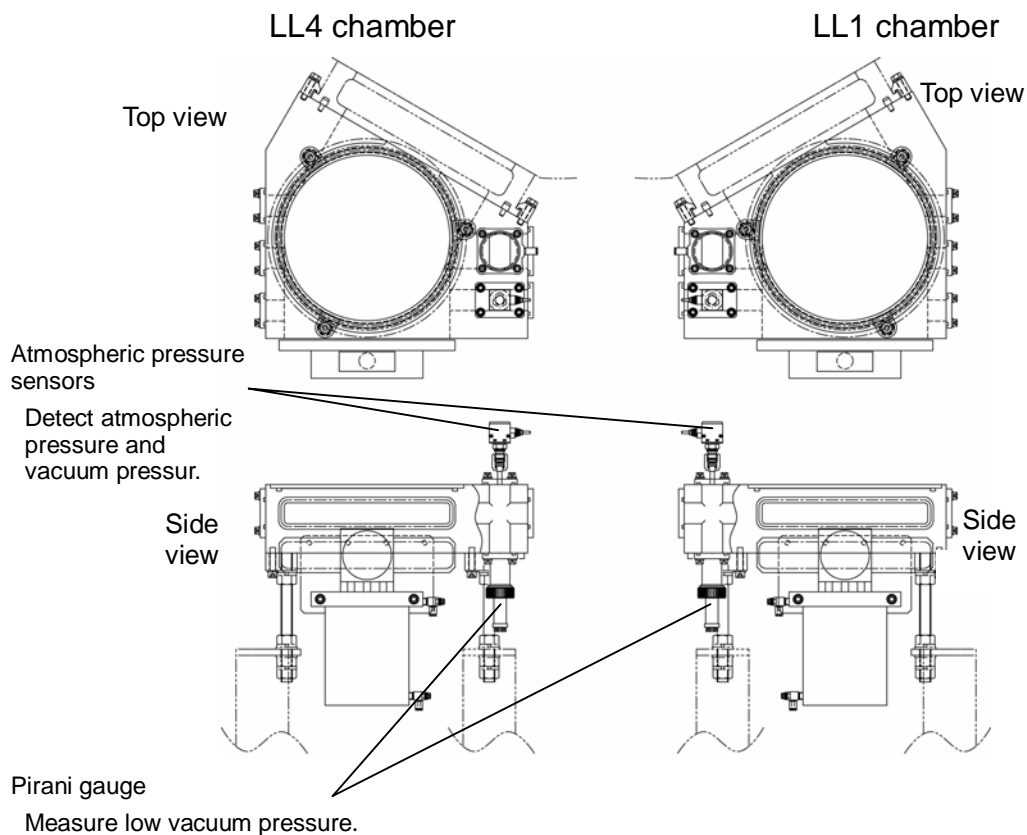
### 2-3. System front elevational view



### 2-4. Rear elevational view

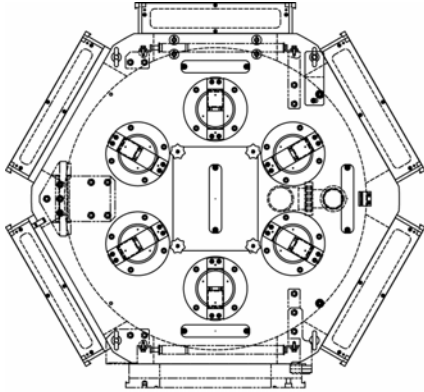


### 2-5. Load-lock chamber

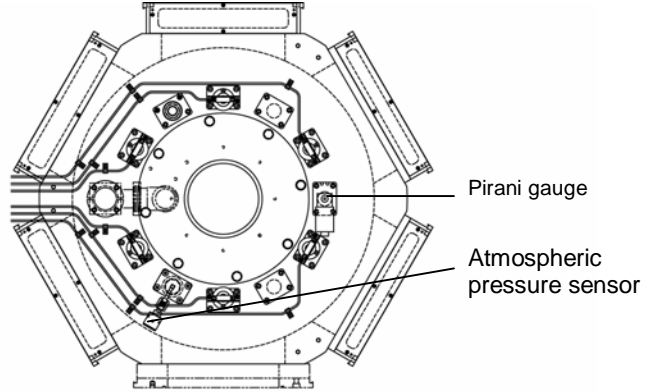


## 2-6. Transport chamber

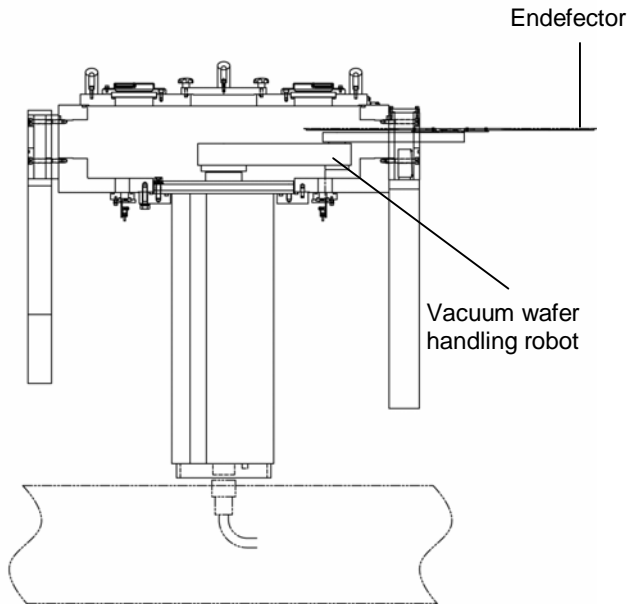
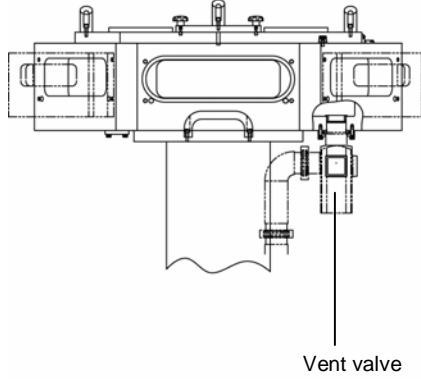
Top view



Bottom view



Side view



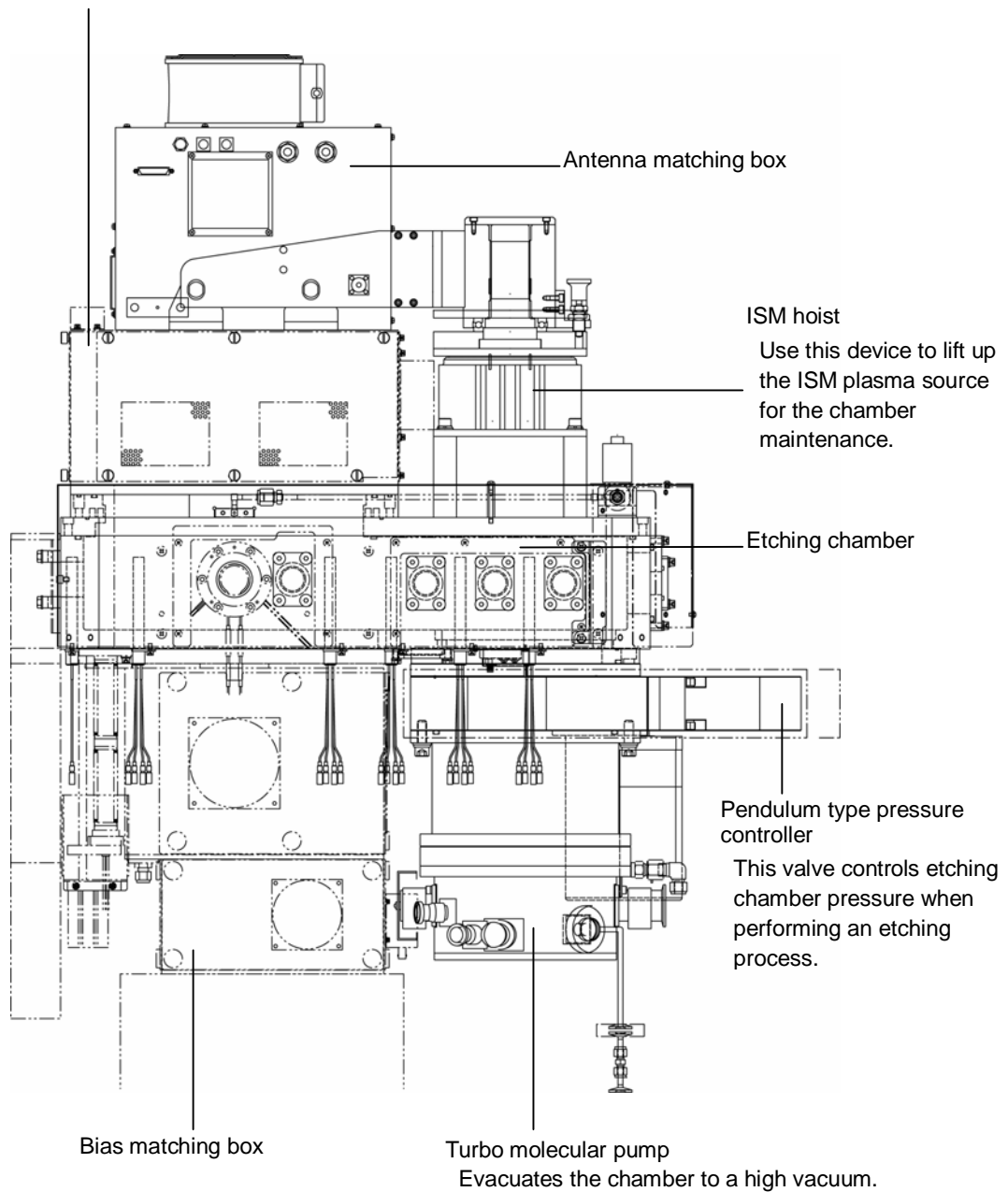
## 2-7. Etching chamber

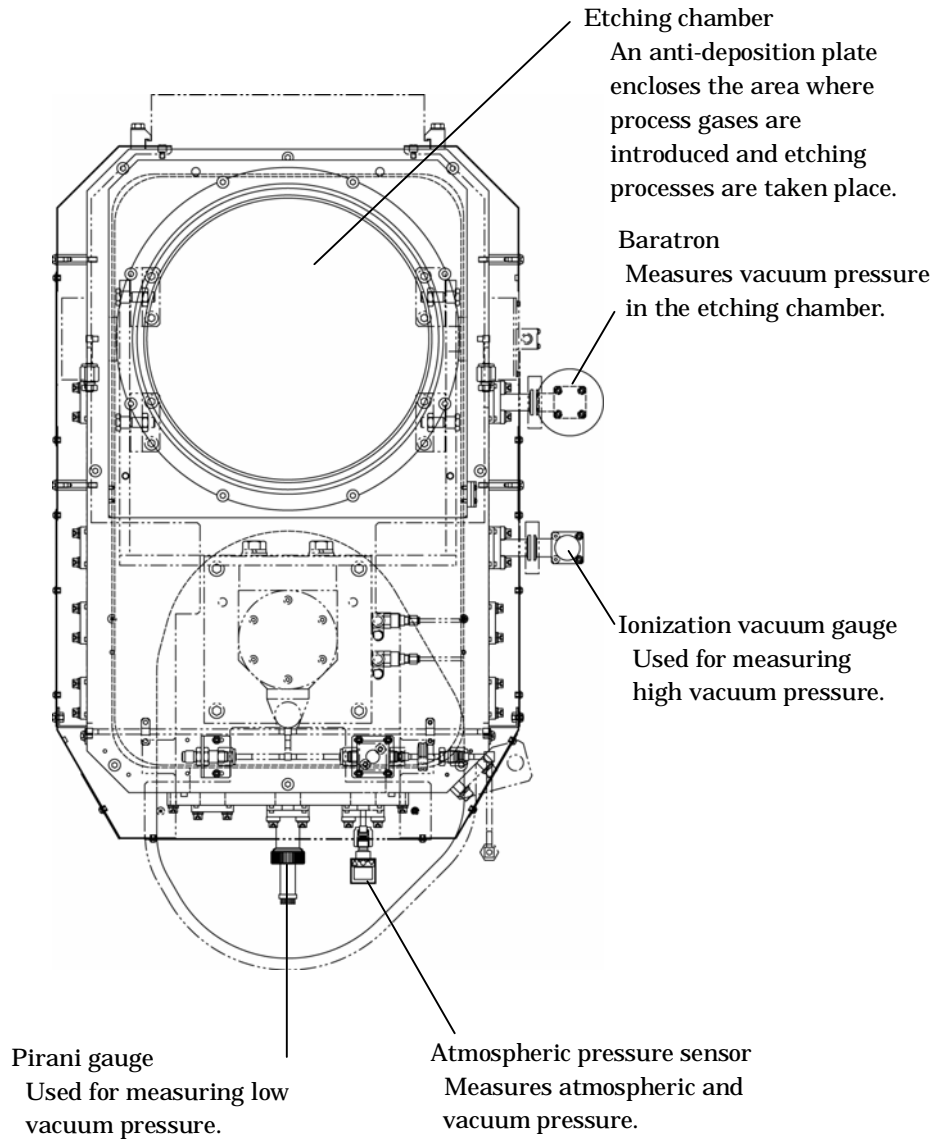
### 2-7-1. Etching chamber 2

#### ISM plasma source

An ISM plasma source is installed in the shield box.

Caution : Make sure that the RF power supply is off when opening the shield box for maintenance.







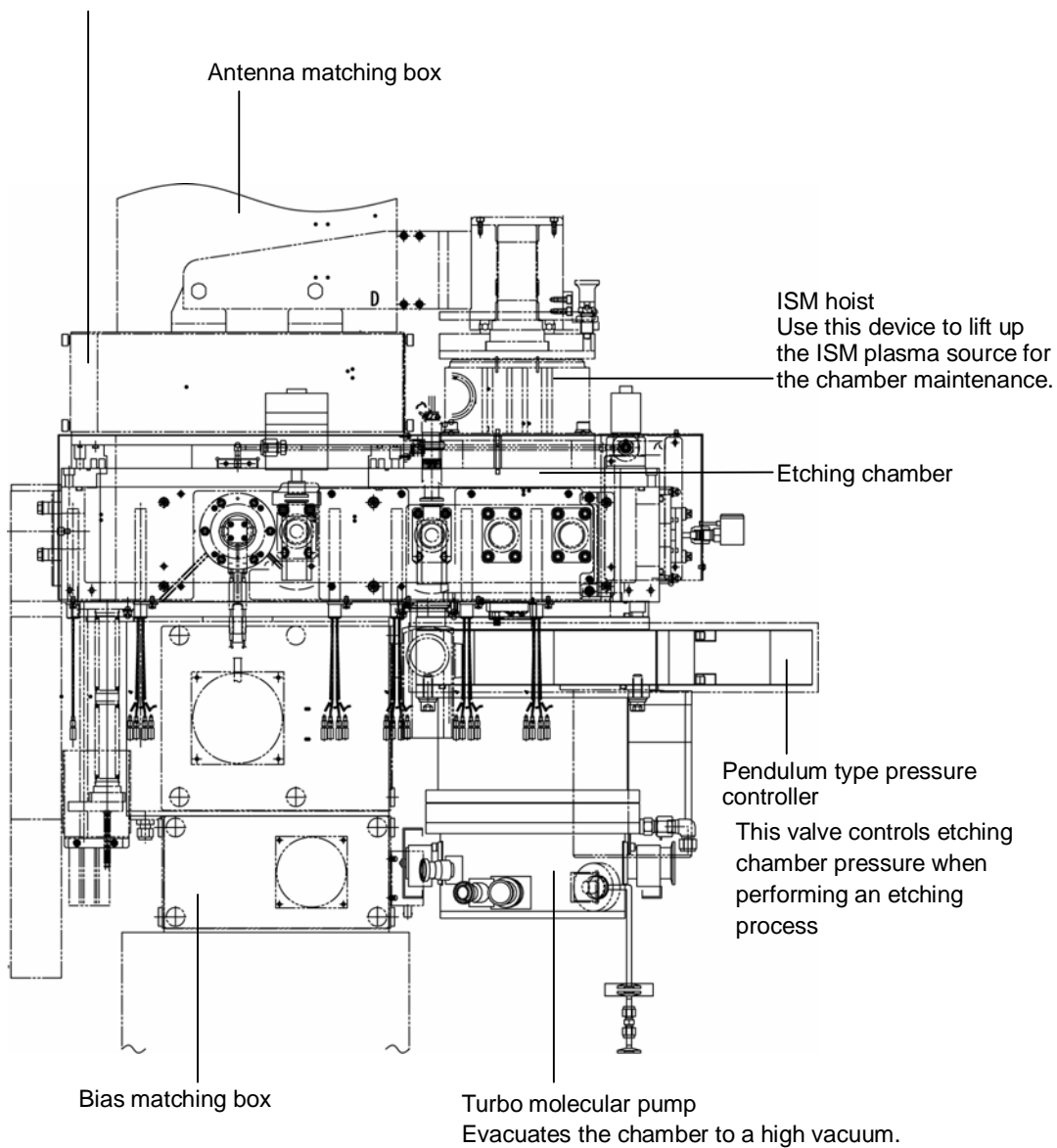
## 2-8. Etching chamber

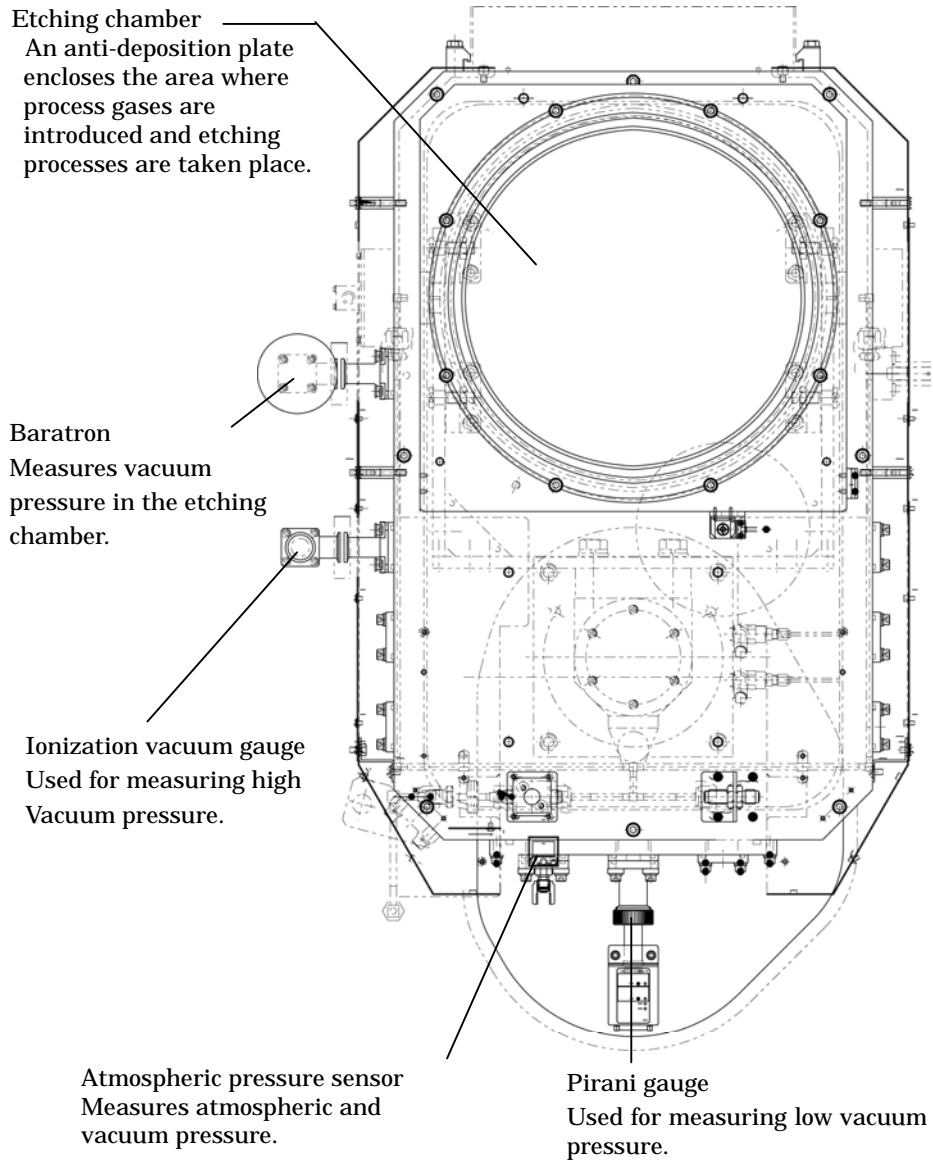
### 2-8-1. Etching chamber 3

#### ISM plasma source

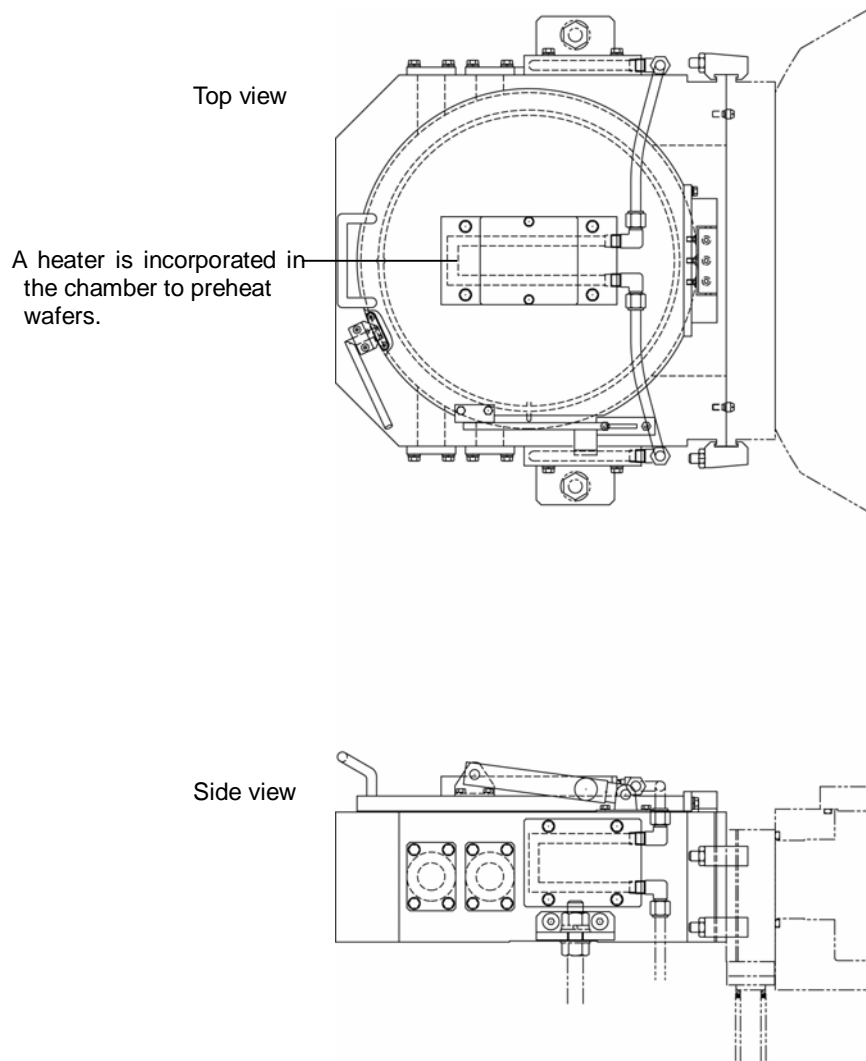
An ISM plasma source is installed in the shield box.

Caution : Make sure that the RF power supply is off when opening the shield box for maintenance.

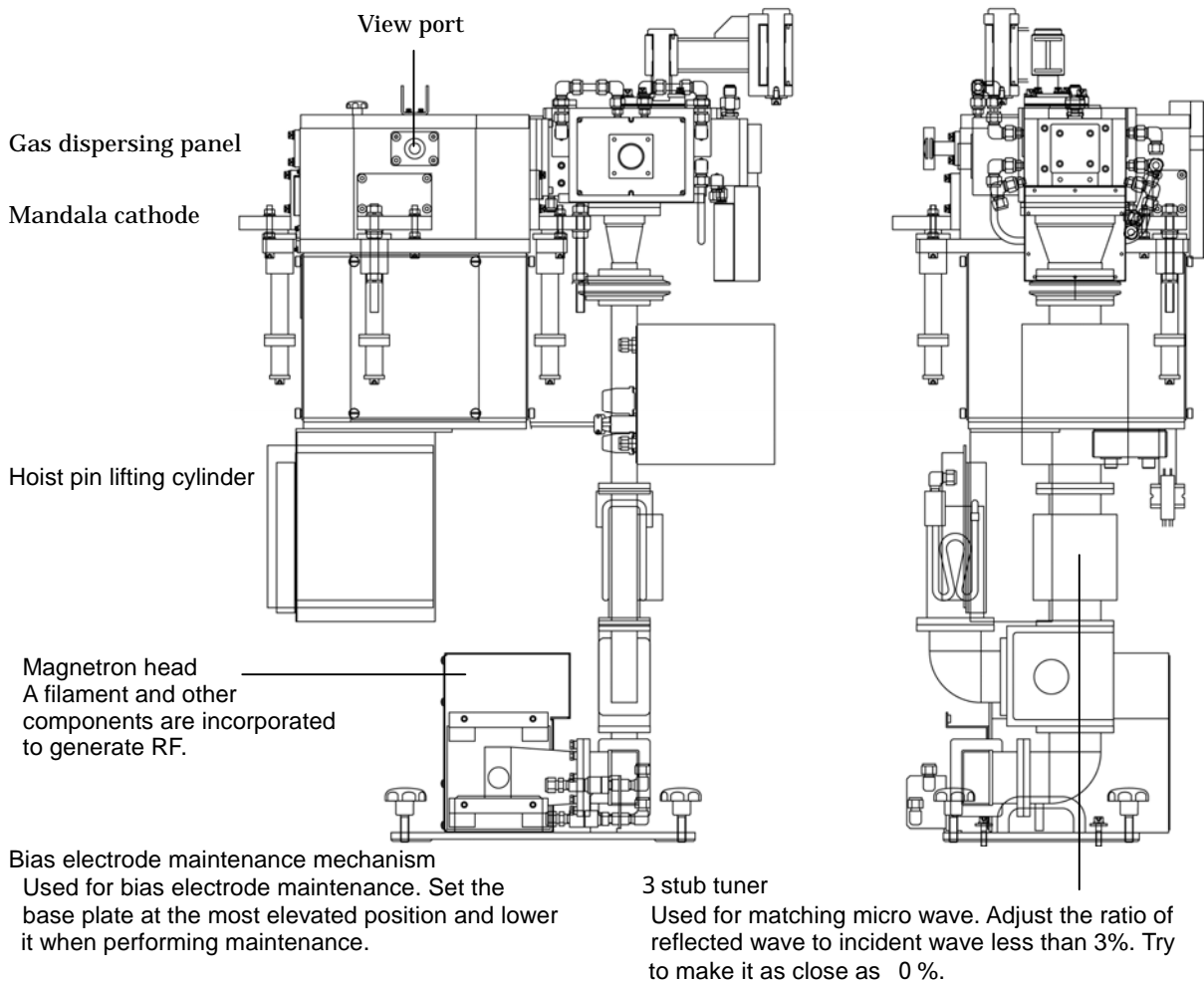
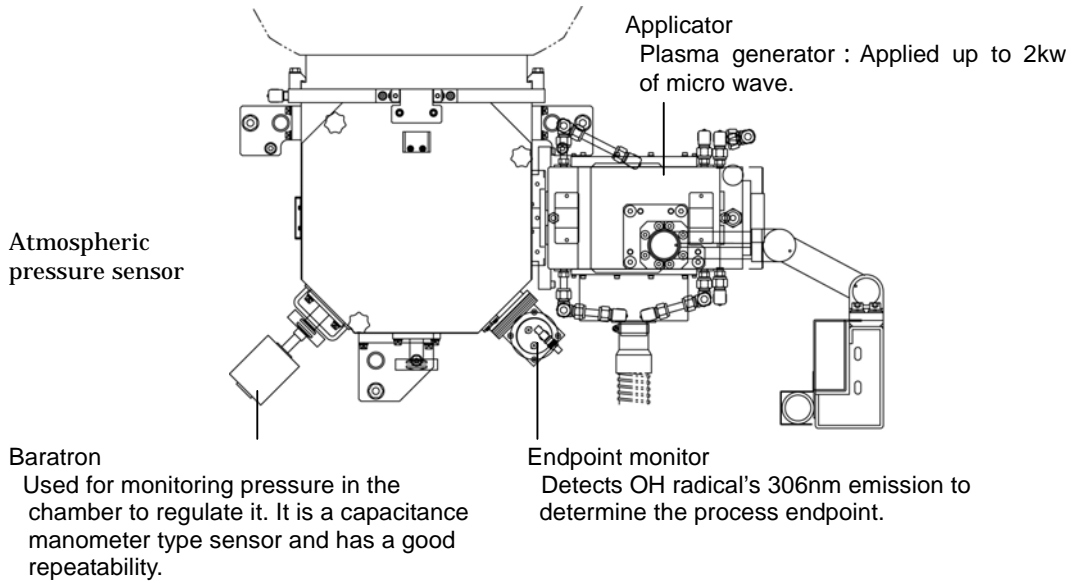




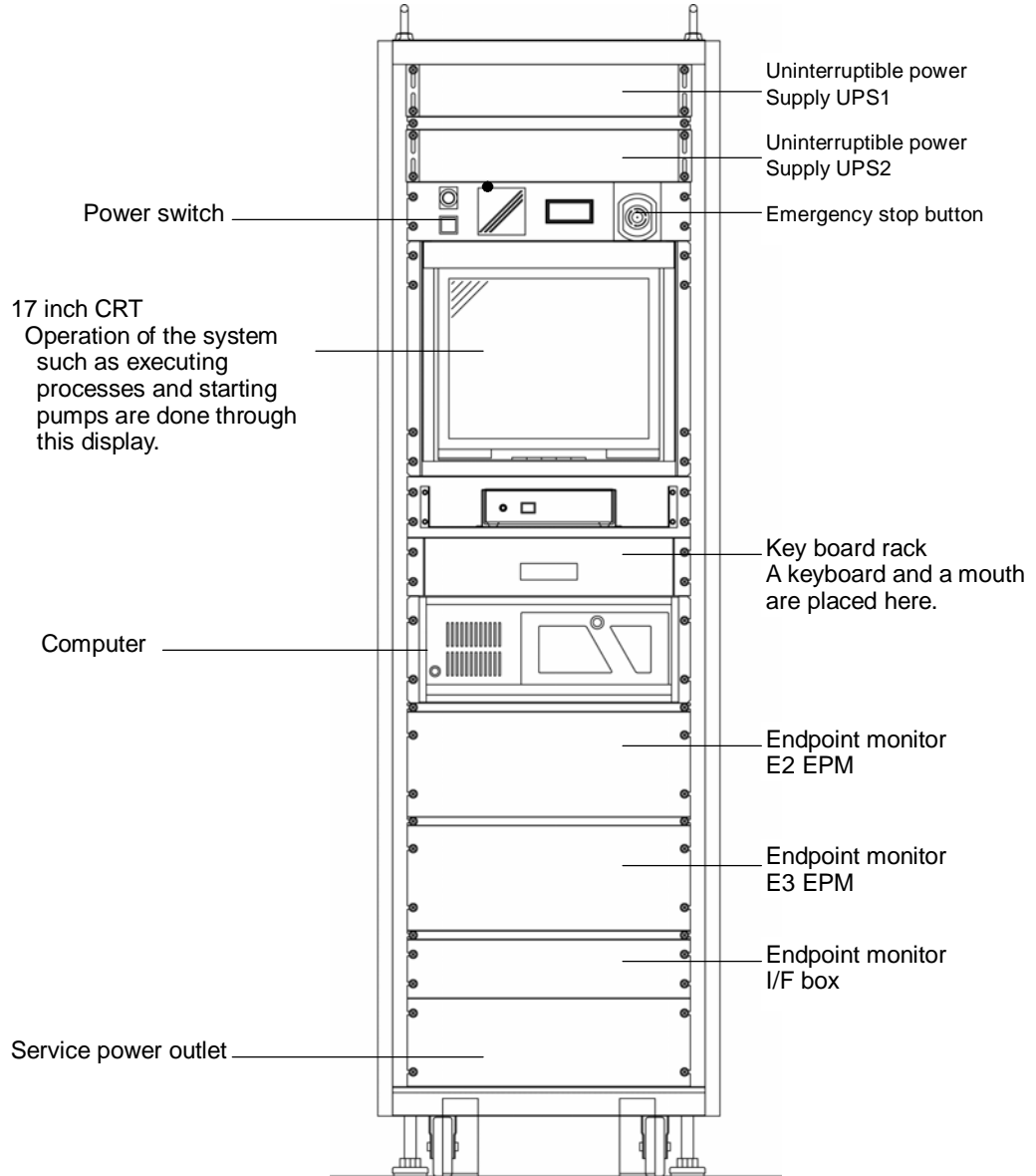
## 2-9. Preheat chamber



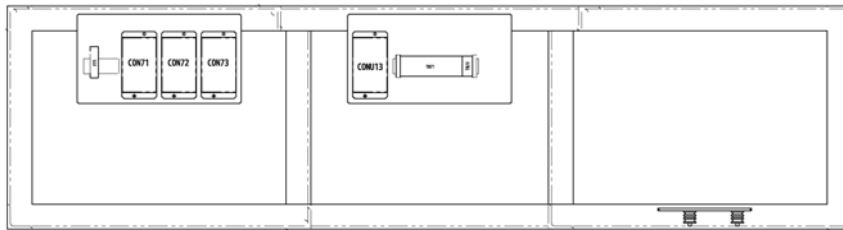
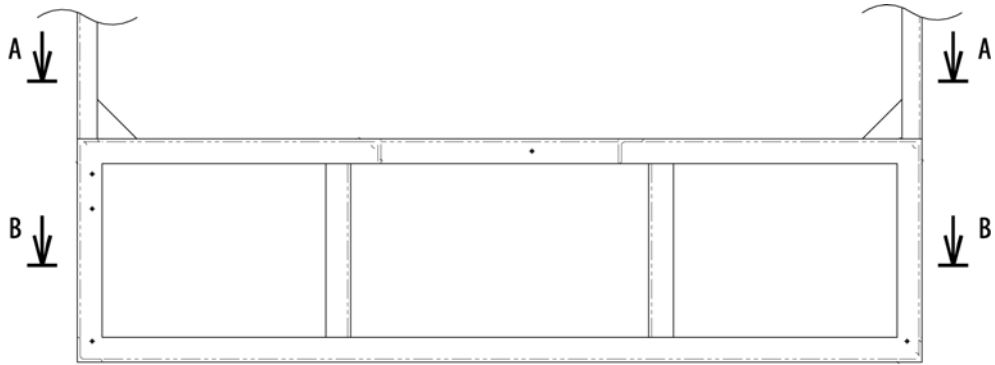
## 2-10. Ashing chamber



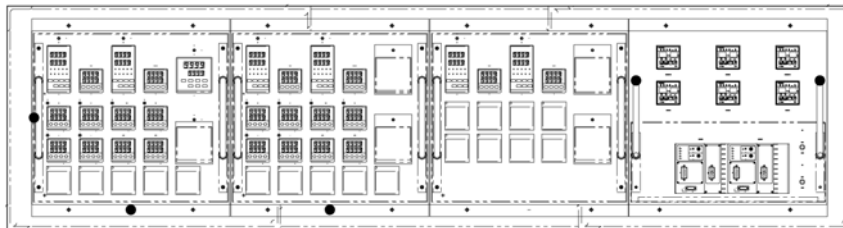
## 2-11. Control cabinet



### 2-12. Temperature controller panel



B-B



A-A

### 2-13. Vacuum pump

Dry pump model numbers.

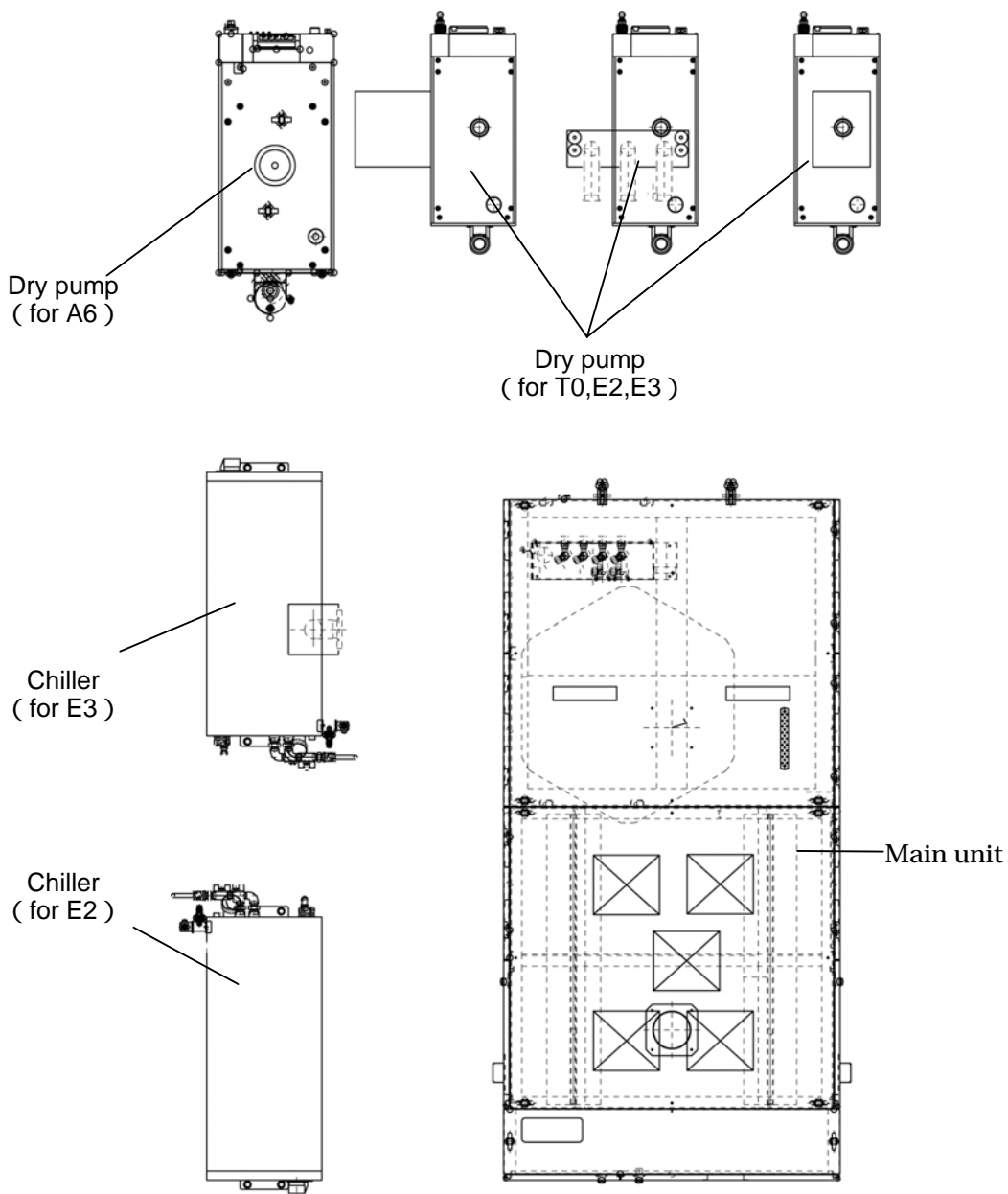
T0,E2,E3 : ESR20N ( Ebara corporation )

A6 : ESR200WN ( Ebara corporation )

Chiller model number.

E 2,E3 : HRZ002-W-X002 ( SMC )

Refer to "The equipment manual" (supplemental) for further information.



**MEMO**